

Vishay General Semiconductor

HALOGEN

FREE

# High Current Density Surface-Mount Glass Passivated Rectifiers



#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS					
I <sub>F(AV)</sub>	8 A				
$V_{RRM}$	400 V, 600 V, 800 V, 1000 V				
I <sub>FSM</sub>	230 A				
I <sub>R</sub>	5 μΑ				
V <sub>F</sub> at I <sub>F</sub> = 8 A	0.87 V				
T <sub>J</sub> max.	150 °C				
Package	SMPC (TO-277A)				
Circuit configuration	Single				

#### **FEATURES**

- Very low profile typical height of 1.1 mm
- · Ideal for automated placement
- · Glass passivated pellet chip junction
- Low forward voltage drop
- · High surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

#### TYPICAL APPLICATIONS

For use in general purpose rectification of power supplies, inverters, converters and freewheeling diodes for consumer, and telecommunication.

#### **MECHANICAL DATA**

Case: SMPC (TO-277A)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	S8PG	S8PJ	S8PK	S8PM	UNIT
Device marking code		S8PG	S8PJ	S8PK	S8PM	
Max. repetitive peak reverse voltage	$V_{RRM}$	400	600	800	1000	V
Average forward current	I <sub>F(AV)</sub> (1)	8				
	I <sub>F(AV)</sub> (2)	2				
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	230			А	
Operating junction and storage temperature range	T <sub>J</sub> <sup>(3)</sup> , T <sub>STG</sub>	-55 to +150			°C	

#### Notes

- (1) Mounted on 3 cm x 3 cm aluminum pad area
- (2) Free air mounted on recommended pad area
- $^{(3)}$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

# S8PG, S8PJ, S8PK, S8PM

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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise noted)							
PARAMETER	TEST CO	TEST CONDITIONS		TYP.	MAX.	UNIT	
Instantaneous forward voltage	I <sub>F</sub> = 4 A	—— T₁ = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.91	-	V	
	I <sub>F</sub> = 8 A			0.97	1.10		
	I <sub>F</sub> = 4 A	T <sub>J</sub> = 125 °C		0.79	-		
	I <sub>F</sub> = 8 A			0.87	0.95		
Reverse current	Rated V <sub>R</sub>	T <sub>J</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	5	μА	
	nateu v <sub>R</sub>	T <sub>J</sub> = 125 °C		92	250		
Max. reverse recovery time	$I_F = 0.5 \text{ A}, I_R$ $I_{rr} = 0.25 \text{ A}$	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A},$ $I_{rr} = 0.25 \text{ A}$		5.0	-	μs	
Typical junction capacitance	4.0 V, 1 MHz	4.0 V, 1 MHz		60	-	pF	

#### **Notes**

 $^{(1)}$  Pulse test: 300  $\mu s$  pulse width, 1 % duty cycle

(2) Pulse test: Pulse width  $\leq$  40 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	S8PG	S8PJ	S8PK	S8PM	UNIT
Typical thermal resistance	R <sub>θJA</sub> (1)(2)	82				°C/W
Typical trieffial resistance	R <sub>0JM</sub> (3)	3.5				C/VV

#### **Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
- (3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)							
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE			
S8PM-M3/H	0.10	Н	1500	7" diameter plastic tape and reel			
S8PM-M3/I	0.10	I	6500	13" diameter plastic tape and reel			

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### **RATINGS AND CHARACTERISTICS CURVES** (T<sub>A</sub> = 25 °C unless otherwise noted)

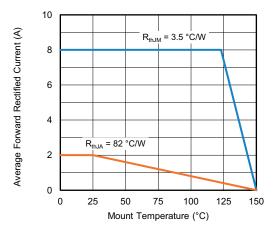


Fig. 1 - Maximum Forward Current Derating Curve

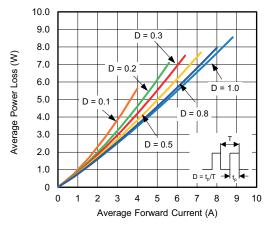


Fig. 2 - Forward Power Loss Characteristics

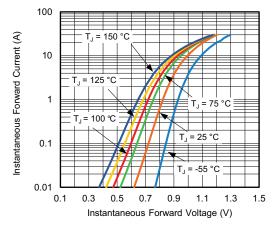


Fig. 3 - Typical Instantaneous Forward Characteristics

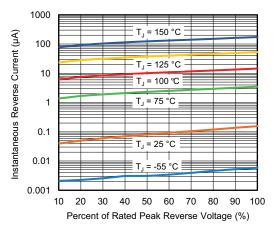


Fig. 4 - Typical Reverse Leakage Characteristics

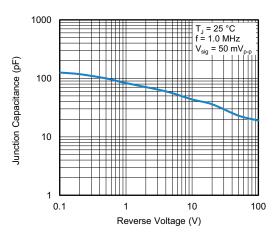


Fig. 5 - Typical Junction Capacitance

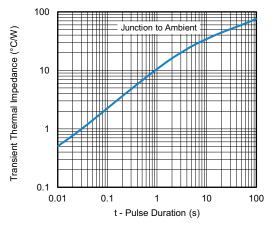
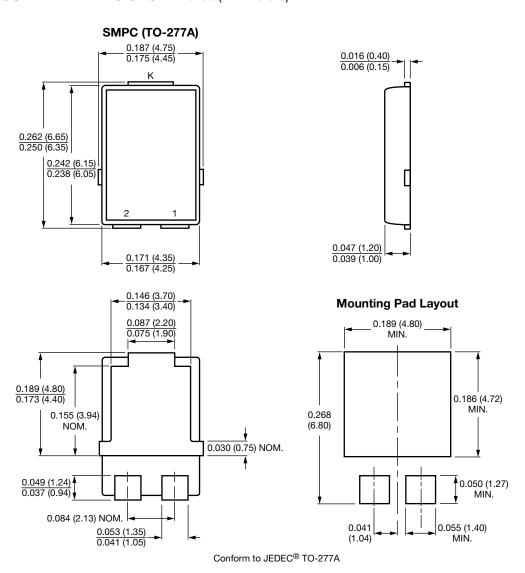


Fig. 6 - Typical Transient Thermal Impedance



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#### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)





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